

SINGLE-CHIP, LI-ION AND LI-POL CHARGER IC WITH AUTONOMOUS USB-PORT AND AC-ADAPTER SUPPLY MANAGEMENT (bqTINY™-II)

FEATURES

- **Small 3 mm × 3 mm MLP Package**
- **Charges and powers Systems from Either AC Adapter or USB With Autonomous power-Source Selection**
- **Integrated USB Control With Selectable 100 mA and 500 mA Charge Rates**
- **Ideal for Low-Dropout Charger Designs for Single-Cell Li-Ion or Li-pol Packs in Space Limited portable applications**
- **Integrated power FET and Current Sensor for Up to 1-A Charge applications From AC Adapter**
- **Precharge Conditioning With Safety Timer**
- **power Good (AC Adapter Present) Status Output**
- **Optional Battery Temperature Monitoring Before and During Charge**
- **Automatic Sleep Mode for Low-power Consumption**

APPLICATIONS

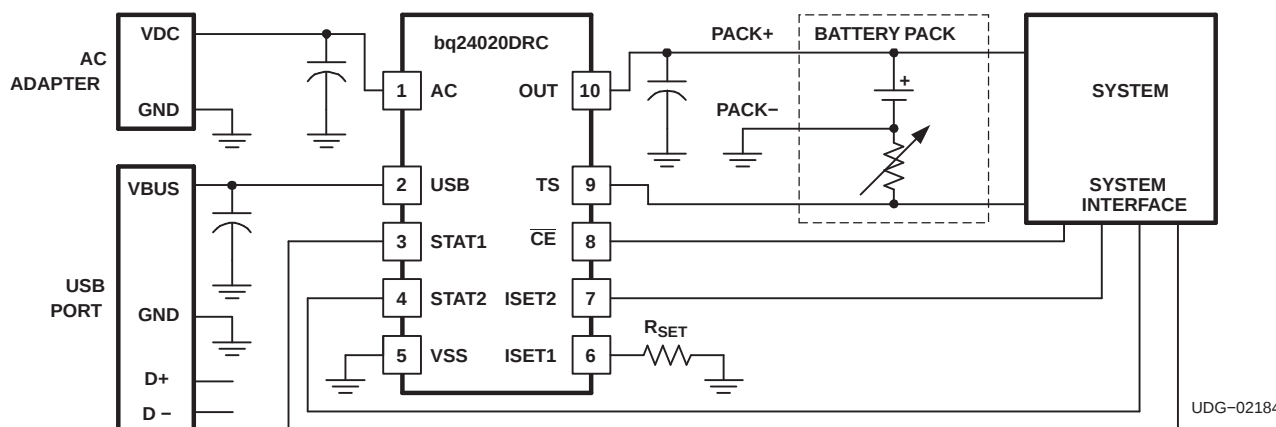
- **PDAs, MP3 Players**
- **Digital Cameras**
- **Internet appliances**
- **Smartphones**

DESCRIPTION

The bqTINY-II series are highly-integrated, flexible Li-Ion linear charge and system power management devices for space-limited charger applications. In a single monolithic device, the bqTINY-II offers integrated USB-port and ac-adapter supply management with autonomous power-source selection, power-FET and current-sensor interfaces, high-accuracy current and voltage regulation, charge status, and charge termination.

The bqTINY-II automatically selects the USB-port or the ac-adapter as the power source for the system. In the USB configuration, the host can select from two preset charge rates of 100 mA or 500 mA. In the ac-adapter configuration, an external resistor sets the system or charge current.

The bqTINY-II charges the battery in three phases: conditioning, constant current, and constant voltage. Charge is terminated based on minimum current. An internal charge timer provides a backup safety for charge termination. The bqTINY-II automatically restarts the charge if the battery voltage falls below an internal threshold. The bqTINY-II automatically enters sleep mode when both supplies are removed.



UDG-02184



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

bqTINY is a trademark of Texas Instruments.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DESCRIPTION CONTINUED

Different versions of the bqTINY-II offer many additional features. These include a temperature-sensor input for detecting hot or cold battery packs, a power-good output ($\overline{PG}$) indicating the presence of input power, a TTL-level charge-enable input ($\overline{CE}$) used to disable or enable the charge process, and a TTL-level timer and taper-detect enable input ($\overline{TTE}$) used to disable or enable the fast-charge timer and charge termination.

ORDERING INFORMATION

T_J	CHARGE REGULATION VOLTAGE (V)(1)	OPTIONAL FUNCTIONS ⁽¹⁾	FAST-CHARGE TIMER (Hours)	TAPER TIMER	USB TAPER THRESHOLD	PART NUMBER(2)	MARKINGS
–40°C to 125°C	4.2	$\overline{CE}$ and TS	5	Yes	10% of ISET1 Level	bq24020DRCR	AZS
	4.2	$\overline{PG}$ and $\overline{CE}$	5	Yes	10% of ISET1 Level	bq24022DRCR	AZU
	4.2	$\overline{CE}$ and $\overline{TTE}$	5	Yes	10% of ISET1 Level	bq24023DRCR	AZV
	4.2	$\overline{TTE}$ and TS	5	Yes	10% of ISET1 Level	bq24024DRCR	AZW
	4.2	$\overline{CE}$ and TS	7	Yes	10% of ISET1 Level	bq24025DRCR	AZX
	4.2	$\overline{TE}$ and TS	7	No	10% of selected USB charge rate	bq24026DRCR	ANR
	4.2	$\overline{PG}$ and $\overline{CE}$	7	No	10% of selected USB charge rate	bq24027DRCR	ANS

(1) The DRC package is available taped and reeled only in quantities of 3,000 devices per reel.

Dissipation Ratings

PACKAGE	θ_{JA}	$T_A < 40^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$
DRC ⁽¹⁾	46.87 $^\circ\text{C/W}$	1.5 W	0.021 W/ $^\circ\text{C}$

(1) This data is based on using the JEDEC High-K board and the exposed die pad is connected to a copper pad on the board. This is connected to the ground plane by a 2×3 via matrix.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		bq24020, bq24022, bq24023, bq24024 bq24025, bq24026 bq24027	UNIT
Input voltage ⁽²⁾	AC, $\overline{CE}$, ISET1, ISET2, OUT, $\overline{PG}$, STAT1, STAT2, $\overline{TE}$, TS, $\overline{TTE}$, USB	–0.3 to 7.0	V
Output sink/source current	STAT1, STAT2, $\overline{PG}$	15	mA
Output current	TS	200	μA
Output current	OUT	1.5	A
Operating free-air temperature range, T_A		–40 to 125	$^\circ\text{C}$
Junction temperature range, T_J			
Storage temperature, T_{stg}		–65 to 150	

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to V_{SS} .

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
Supply voltage (from AC input), V_{CC}	4.5		6.5	V
Supply voltage (from USB input), V_{CC}	4.35		6.5	V
Operating junction temperature range, T_J	–40		125	°C

ELECTRICAL CHARACTERISTICS

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and recommended supply voltage, unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
INPUT CURRENT							
I _{CC} (V _{CC})	V _{CC} current	V _{CC} > V _{CC(min)}		1.2	2.0	mA	
I _{CC} (SLP)	Sleep current	Sum of currents into OUT pin, V _{CC} < V _(SLP)		2	5	μA	
I _{CC} (STBY)	Standby current	CE = High 0°C ≤ T _J ≤ 85°C		1	150		
I _B (OUT)	Input current on OUT pin	Charge DONE V _{CC} > V _{CC(MIN)}			5		
I _B (CE)	Input current on CE pin				1		
I _B (TTE)	Input bias current on TTE pin				1		
I _B (TE)	Input bias current on TE pin				1		
VOLTAGE REGULATION V _{O(REG)} + V _(DO-MAX) ≤ V _{CC} , I _(TERM) < I _{O(OUT)} ≤ 1 A							
V _{O(REG)}	Output voltage,			4.20		V	
	Voltage regulation accuracy	T _A = 25°C		−0.35%	0.35%		
				−1%	1%		
V _(DO)	AC dropout voltage (V _(AC) −V _(OUT))	V _{O(OUT)} = V _{O(REG)} V _{O(REG)} + V _(DO-MAX) ≤ V _{CC} I _{O(OUT)} = 1A		350	500	mV	
V _(DO)	USB dropout voltage (V _(USB) − V _(OUT))	V _{O(OUT)} = V _{O(REG)} V _{O(REG)} + V _(DO-MAX) ≤ V _{CC} ISET2 = High		350	500		
		V _{O(OUT)} = V _{O(REG)} V _{O(REG)} + V _(DO-MAX) ≤ V _{CC} ISET2 = Low		60	100		
CURRENT REGULATION							
I _{O(OUT)}	AC output current range ⁽¹⁾	V _{I(OUT)} > V _(LOWV) V _{I(AC)} − V _{I(OUT)} > V _(DO-MAX) V _{CC} ≥ 4.5 V		50	1000	mA	
I _{O(OUT)}	USB output current range	V _{CC(MIN)} ≥ 4.5 V V _{USB} − V _{I(OUT)} > V _(DO-MAX) V _{I(OUT)} > V _(LOWV) ISET2 = Low		80	100		
		V _{CC(MIN)} ≥ 4.5 V V _{USB} − V _{I(OUT)} > V _(DO-MAX) V _{I(OUT)} > V _(LOWV) ISET2 = High		400	500		
V _(SET)	Output current set voltage	Voltage on ISET1 pin, V _{CC} ≥ 4.5 V, V _{IN} ≥ 4.5 V, V _{I(OUT)} > V _(LOWV) , V _{IN} − V _{I(OUT)} > V _(DO-MAX)		2.463	2.500	2.538	V
K _(SET)	Output current set factor	50 mA ≤ I _{O(OUT)} ≤ 1 A		307	322	337	
		10 mA ≤ I _{O(OUT)} < 50 mA		296	320	346	
		1 mA ≤ I _{O(OUT)} < 10 mA		246	320	416	

$$(1) \quad I_{O(\text{OUT})} = \frac{(K_{(\text{SET})} \times V_{(\text{SET})})}{R_{\text{SET}}}$$

ELECTRICAL CHARACTERISTICS (continued)

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and recommended supply voltage, unless otherwise noted

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
PRECHARGE AND SHORT-CIRCUIT CURRENT REGULATION							
V _(LOWV)	Precharge to fast-charge transition threshold		Voltage on OUT pin	2.8	3.0	3.2	V
	Deglitch time for fast-charge to precharge transition		V _{CC(MIN)} ≥ 4.5 V, t _{FALL} = 100 ns, 10 mV overdrive, V _{I(OUT)} decreasing below threshold	250	375	500	ms
I _{O(PRECHG)}	Precharge range ⁽²⁾		0 V < V _{I(OUT)} < V _(LOWV) , t < t _(PRECHG)	5		100	mA
V _(PRECHG)	Precharge set voltage		Voltage on ISET1 pin 0 V < V _{I(OUT)} > V _(LOWV) , V _{O(REG)} = 4.2 V t < t _(PRECHG)	240	255	270	mV
CHARGE TAPER AND TERMINATION DETECTION							
I _(TAPER)	Charge taper detection range ⁽³⁾		V _{I(OUT)} > V _(RCH) , t < t _(TAPER)	5		100	mA
	USB-100 charge taper detection level	bq24026	V _{I(OUT)} > V _(RCH) , ISET2 = Low	6.5	9	11	
	USB-500 charge taper detection level	bq24026	V _{I(OUT)} > V _(RCH) , ISET2 = High	32	44	55	
V _(TAPER)	Charge taper detection set voltage		Voltage on ISET1 pin, V _{O(REG)} = 4.2 V, V _{I(OUT)} > V _(RCH) , t < t _(TAPER)	235	250	265	mV
V _(TERM)	Charge termination detection set voltage ⁽⁴⁾		Voltage on ISET1 pin, V _{O(REG)} = 4.2 V, V _{I(OUT)} > V _(RCH)	11	18	25	
t _(TPRDET)	Deglitch time for TAPER detection		V _{CC(MIN)} ≥ 4.5 V, t _{FALL} = 100 ns charging current increasing or decreasing above and below, 10 mV overdrive	250	375	500	ms
t _(TRMDET)	Deglitch time for termination detection		V _{CC(MIN)} ≥ 4.5 V, t _{FALL} = 100 ns charging current decreasing below, 10 mV overdrive	250	375	500	
TEMPERATURE SENSE COMPARATOR							
V _(HTF)	High-voltage threshold		PTC thermistor	2.475	2.500	2.525	V
V _(LTF)	Low-voltage threshold		PTC thermistor	0.485	0.500	0.515	
I _(TS)	Current source			96	102	108	μA
t _(DEGL)	Deglitch time for temperature fault			250	375	500	ms

$$(2) \quad I_{\text{O}(\text{PRECHG})} = \frac{(K_{(\text{SET})} \times V_{(\text{PRECHG})})}{R_{\text{SET}}}$$

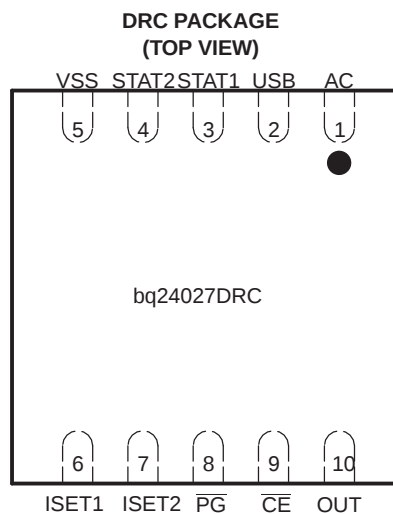
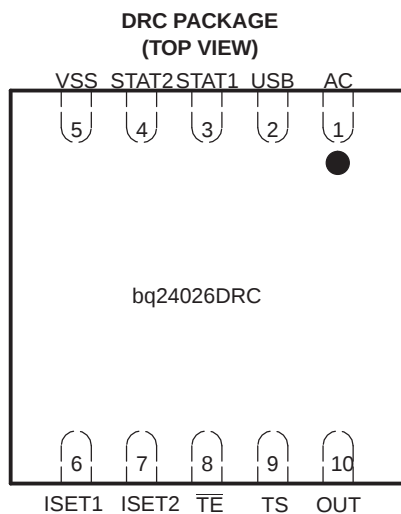
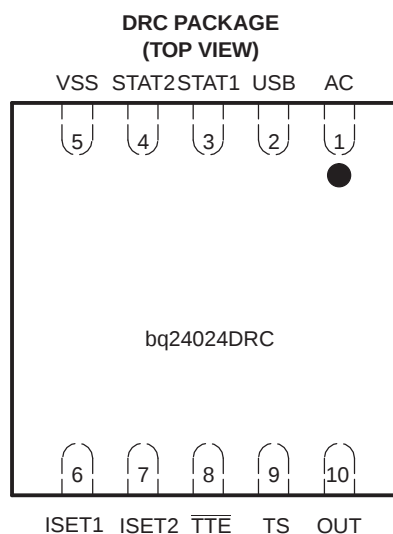
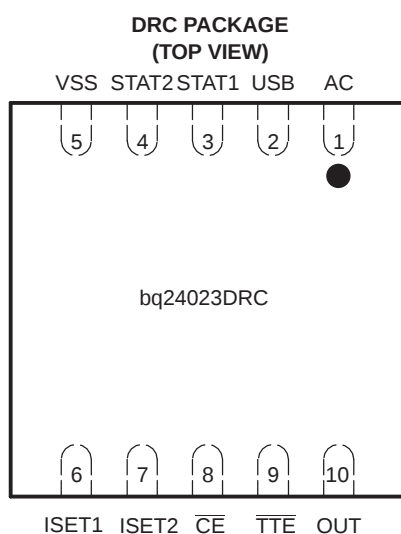
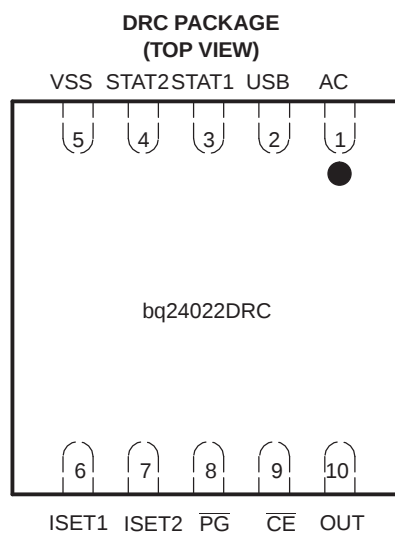
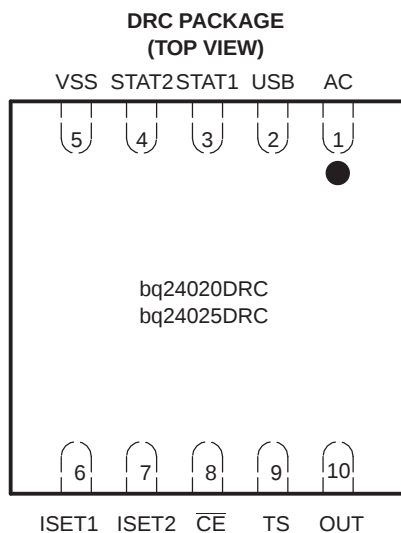
$$(3) \quad I_{\text{O}(\text{TAPER})} = \frac{(K_{(\text{SET})} \times V_{(\text{TAPER})})}{R_{\text{SET}}}$$

$$(4) \quad I_{\text{O}(\text{TERM})} = \frac{(K_{(\text{SET})} \times V_{(\text{TERM})})}{R_{\text{SET}}}$$

ELECTRICAL CHARACTERISTICS (continued)

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and recommended supply voltage, unless otherwise noted

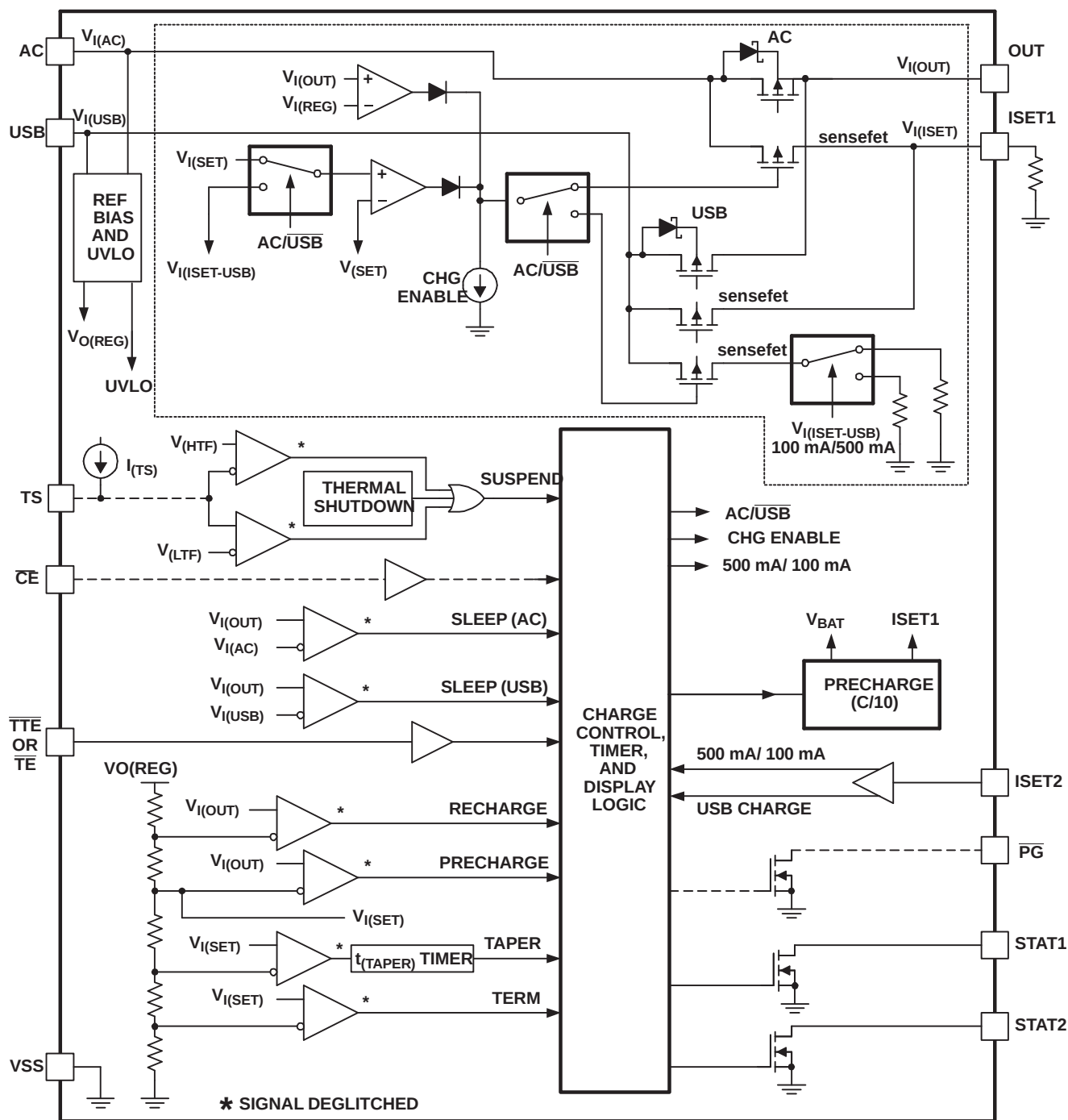
PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
BATTERY RECHARGE THRESHOLD							
V _{RCH}	Recharge threshold			V _{O(REG)} − 0.115	V _{O(REG)} − 0.10	V _{O(REG)} − 0.085	V
t _(DEGL)	Deglitch time for recharge detect		V _{CC(MIN)} ≥ 4.5 V, t _{FALL} = 100 ns decreasing below or increasing above threshold, 10 mV overdrive	250	375	500	ms
STAT1, STAT2, and PG OUTPUTS							
V _{OL}	Low-level output saturation voltage		I _O = 5 mA	0.25			V
ISET2, CHARGE ENABLE (CE), TIMER AND TERMINATION ENABLE (TTE), AND TIMER ENABLE (TE) INPUTS							
V _{IL}	Low-level input voltage		I _{IL} = 10 μA	0	0.4		V
V _{IH}	High-level input voltage		I _{IL} = 20 μA	1.4			
I _{IL}	CE, TE or TTE low-level input current			−1			μA
I _{IH}	CE, TE or TTE high-level input current			1			
I _{IL}	ISET2 low-level input current		I _{ISET2} = 0	−20			
I _{IH}	ISET2 high-level input current		I _{ISET2} = V _{CC}	40			
I _{IH}	ISET2 high-Z input current			1		V	
TIMERS							
t _(PRECHG)	Precharge time			1,584	1,800	2,016	s
t _(TAPER)	Taper time	bq24020 bq24022 bq24023 bq24024 bq24025		1,584	1,800	2,016	
t _(CHG)	Charge time	bq24020 bq24022 bq24023 bq24024		15,840	18,000	20,160	
		bq24025 bq24026 bq24027		22,176	25,200	28,224	
I _(FAULT)	Timer fault recovery current			200			μA
SLEEP COMPARATOR							
V _(SLP)	Sleep-mode entry threshold voltage		2.3 V ≤ V _{I(OUT)} ≤ V _{O(REG)}	V _{CC} ≤ V _{I(OUT)} + 80 mV			V
V _(SLPEXIT)	Sleep mode exit threshold voltage		2.3 V ≤ V _{I(OUT)} ≤ V _{O(REG)}	V _{CC} ≥ V _{I(OUT)} + 190mV			
Sleep mode deglitch time			AC and USB decreasing below threshold, t _{FALL} = 100 ns, 10 mV overdrive	250	375	500	ms
THERMAL SHUTDOWN THRESHOLDS							
T _(SHTDWN)	Thermal trip threshold			165			°C
Thermal hysteresis				15			
UNDERVOLTAGE LOCKOUT							
V _(UVLO)	Undervoltage lockout		Decreasing V _{CC}	2.4	2.5	2.6	V
Hysteresis				27			mV



Terminal Functions

NAME	TERMINAL					I/O	DESCRIPTION
	bq24020 bq24025	bq24022 bq24027	bq24023	bq24024	bq24026		
AC	1	1	1	1	1	I	AC charge input voltage
$\overline{CE}$	8	9	8	-	-	I	Charge enable input (active low)
ISSET1	6	6	6	6	6	I	Charge current set point for AC input and precharge and taper set point for both AC and USB
ISSET2	7	7	7	7	7	I	Charge current set point for USB port (high=500 mA, low=100 mA, hi-z = disable USB charge)
OUT	10	10	10	10	10	O	Charge current output
$\overline{PG}$	-	8	-	-	-	O	powergood status output (active low)
STAT1	3	3	3	3	3	O	Charge status output 1 (open-drain)
STAT2	4	4	4	4	4	O	Charge status output 2 (open-drain)
$\overline{TE}$	-	-	-	-	8	I	Timer enable input (active low)
TS	9	-	-	9	9	I	Temperature sense input
$\overline{TTE}$	-	-	9	8	-	I	Timer and termination enable input (active low)
USB	2	2	2	2	2	I	USB charge input voltage
VSS	5	5	5	5	5	-	Ground input
Exposed Thermal Pad	pad	pad	pad	pad	pad	-	There is an internal electrical connection between the exposed thermal pad and VSS pin of the device. The exposed thermal pad must be connected to the same potential as the VSS pin on the printed circuit board. Do not use the thermal pad as the primary ground input for the device. VSS pin must be connected to ground at all times

FUNCTIONAL BLOCK DIAGRAM



UDG-02185

TYPICAL CHARACTERISTICS

AC DROPOUT VOLTAGE

VS

JUNCTION TEMPERATURE

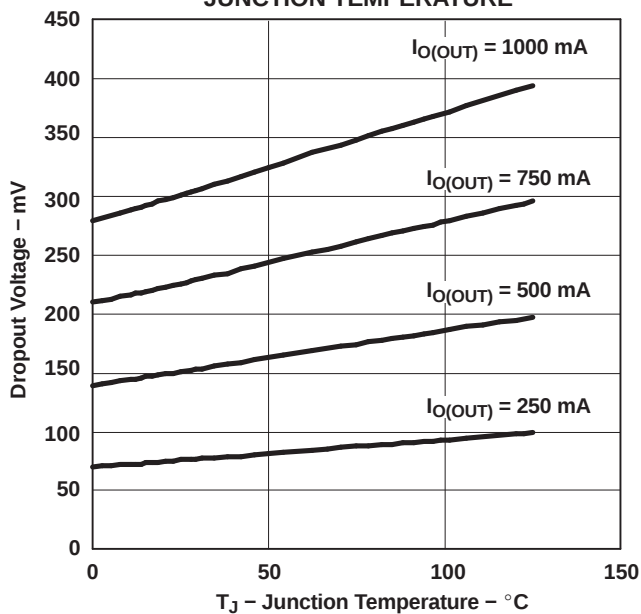


Figure 1.

The bqTINY-II supports a precision Li-Ion, Li-pol charging system suitable for single-cell packs. Figure 3 shows a typical charge profile, application circuit and Figure 4 shows an operational flow chart.

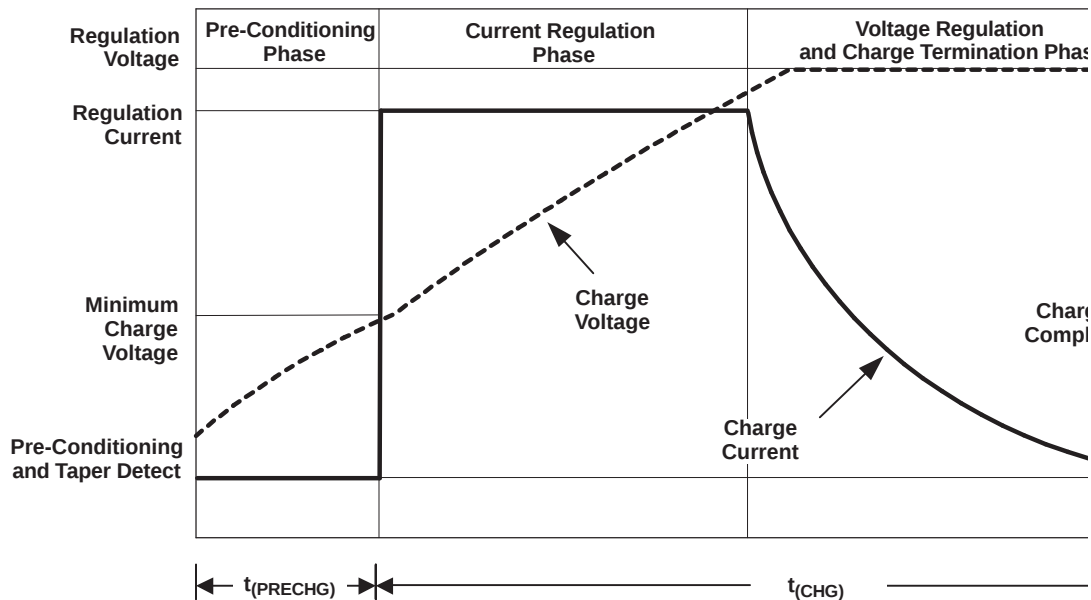
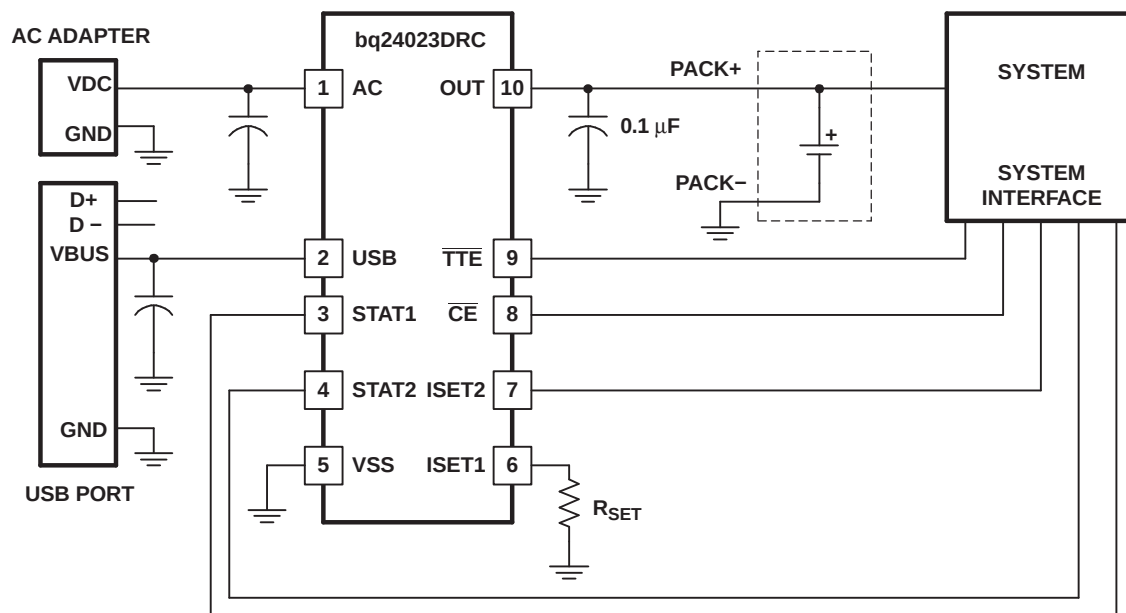


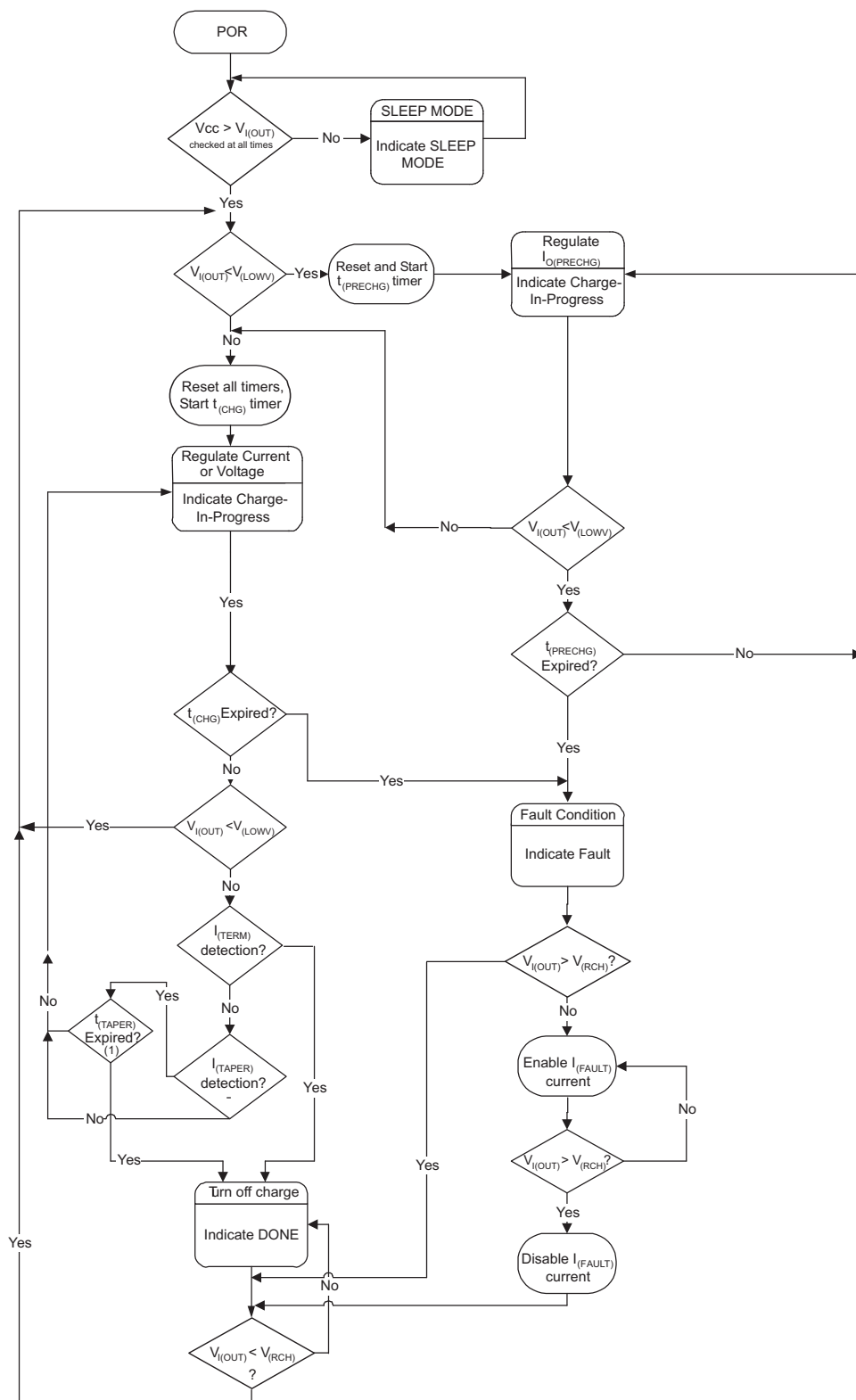
Figure 2. Typical Charging Profile

FUNCTIONAL DESCRIPTION



UDG-02184

Figure 3. Typical Application Circuit

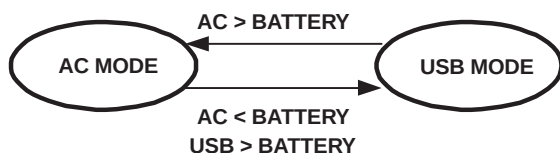


(1) t_{TAPER} does not apply to bq24026/7

Figure 4. Operational Flow Chart

AUTONOMOUS POWER SOURCE SELECTION

As default, the bqTINY-II attempts to charge from the AC input. If AC input is not present, the USB is selected. If both inputs are available, the AC adapter has the priority. See for details.



UDG-02187

Figure 5. Typical Charging Profile

TEMPERATURE QUALIFICATION (bq24020, bq24024, bq24025, and bq24026 only)

The bqTINY-II continuously monitors battery temperature by measuring the voltage between the TS and VSS pins. An internal current source provides the bias for common 10-kΩ negative-temperature coefficient thermistors (NTC) (see Figure 6). The device compares the voltage on the TS pin with the internal $V_{(LTF)}$ and $V_{(HTF)}$ thresholds to determine if charging is allowed. If a temperature outside the $V_{(LTF)}$ and $V_{(HTF)}$ thresholds is detected, the device immediately suspends the charge by turning off the power FET and holding the timer value (i.e. timers are NOT reset). Charge is resumed when the temperature returns within the normal range.

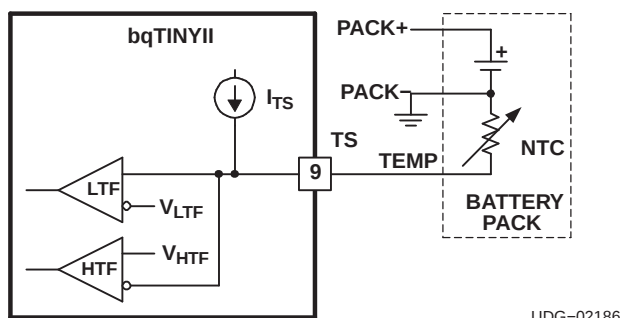
The allowed temperature range for a 103AT-type thermistor is 0°C to 45°C. However the user may modify these thresholds by adding two external resistors. See Figure 7.

BATTERY PRE-CONDITIONING

If the battery voltage falls below the $V_{(LOWV)}$ threshold during a charge cycle, the bqTINY-II applies a precharge current, $I_{O(PRECHG)}$, to the battery. This feature revives deeply discharged cells. The resistor connected between the ISET1 and V_{SS} , R_{SET} , determines the precharge rate. The $V_{(PRECHG)}$ and $K_{(SET)}$ parameters are specified in the specifications table. Note that this applies to both AC and USB charging.

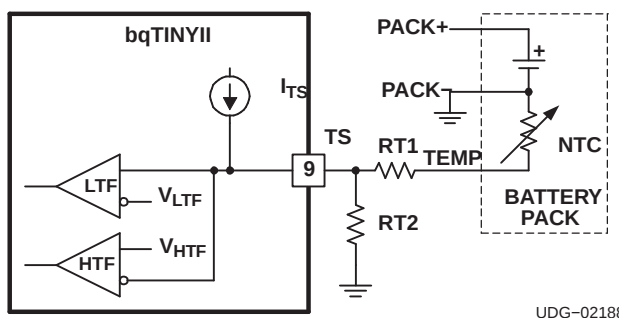
$$I_{O(PRECHG)} = \frac{V_{(PRECHG)}}{R_{SET}} \cdot K_{(SET)} \quad (1)$$

The bqTINY-II activates a safety timer, $t_{(PRECHG)}$, during the conditioning phase. If $V_{(LOWV)}$ threshold is not reached within the timer period, the bqTINY-II turns off the charger and asserts a FAULT code on the STATx pins. Please refer to the *TIMER FAULT RECOVERY* section for additional details.



UDG-02186

Figure 6. Temperature Sensing Configuration



UDG-02188

Figure 7. Temperature Sensing Thresholds

BATTERY CHARGE CURRENT

The bqTINY-II offers on-chip current regulation with a programmable set point. The resistor connected between the ISET1 and V_{SS} , R_{SET} , determines the AC charge rate. The $V_{(SET)}$ and $K_{(SET)}$ parameters are specified in the specifications table.

$$I_{O(OUT)} = \frac{(K_{(SET)} \times V_{(SET)})}{R_{SET}} \quad (2)$$

When charging from a USB port, the host controller has the option of selecting either a 100-mA or a 500-mA charge rate using the ISET2 pin. A low-level signal sets the current at 100 mA, and a high-level signal sets the current at 500 mA. A high-Z input disables USB charging.

BATTERY VOLTAGE REGULATION

The voltage regulation feedback is through the OUT pin. This input is tied directly to the positive side of the battery pack. The bqTINY-II monitors the battery-pack voltage between the OUT and V_{SS} pins. When the battery voltage rises to the $V_{O(REG)}$ threshold, the voltage-regulation phase begins and the charging current begins to taper down.

As a safety backup, the bqTINY-II also monitors the charge time. If the charge is not terminated within the time period specified by $t_{(CHG)}$, the bqTINY-II turns off the charger and asserts a FAULT code on the STATx pins. Please refer to the *TIMER FAULT RECOVERY* section for additional details.

CHARGE TAPER DETECTION, TERMINATION AND RECHARGE

The bqTINY-II monitors the charging current during the voltage-regulation phase. When the taper threshold, $I_{(TAPER)}$, is detected, the bqTINY-II initiates the taper timer, $t_{(TAPER)}$. Charge is terminated after the timer expires. The resistor connected between the ISET1 and V_{SS} , R_{SET} , determines the taper detection level. The $V_{(TAPER)}$ and $K_{(SET)}$ parameters are specified in the specifications table. Note that this applies to both AC and USB charging.

$$I_{(TAPER)} = \frac{V_{(TAPER)} \times K_{(SET)}}{R_{SET}} \quad (3)$$

The bqTINY-II resets the taper timer if the charge current rises above the taper threshold, $I_{(TAPER)}$.

In addition to taper-current detection, the bqTINY-II terminates charge if the charge current falls below the $I_{(TERM)}$ threshold. This feature allows quick recognition of a battery-removal condition, or insertion of a fully charged battery. Note that the charge timer and taper timer are bypassed for this feature. The resistor connected between the ISET1 and V_{SS} , R_{SET} , determines the taper detection level. The $V_{(TERM)}$ and $K_{(SET)}$ parameters are specified in the specifications table. Note that this applies to both AC and USB charging.

$$I_{(TERM)} = \frac{V_{(TERM)} \times K_{(SET)}}{R_{SET}} \quad (4)$$

After charge termination, the bqTINY-II re-starts the charge when the voltage on the OUT pin falls below the $V_{(RCH)}$ threshold. This feature keeps the battery at full capacity at all times.

Note ON bq24026 AND bq24027

The bq24026 and bq24027 monitor the charging current during the voltage-regulation phase. Once the taper threshold, $I_{(TAPER)}$, is detected, the bq24026/27 terminates the charge. There is no taper timer ($t_{(TAPER)}$) for this version.

The resistor connected between the ISET1 and V_{SS} , R_{SET} , determines the taper-detect level for AC input. For USB charge, taper level is fixed at 10% of the 100- or 500-mA charge rate.

Also note that there is $I_{(TERM)}$ detection in the bq24026 and the bq24027.

SLEEP MODE

The bqTINY-II enters low-power sleep mode if both AC and USB are removed from the circuit. This feature prevents draining the battery in the absence of input supply.

CHARGE STATUS OUTPUTS

The open-drain STAT1 and STAT2 outputs indicate various charger operations as shown in the following table. These status pins can be used to drive LEDs or communicate to the host processor. Note that OFF indicates the open-drain transistor is turned off.

Table 1. Status Pins Summary⁽¹⁾

CHARGE STATE	STAT1	STAT2
Precharge in progress	ON	ON
Fast charge in progress	ON	OFF
Charge done	OFF	ON
Charge suspend (temperature)	OFF	OFF
Timer fault	OFF	OFF
Sleep mode	OFF	OFF

(1) OFF means the open-drain output transistor on the STAT1 and STAT2 pins is in an off state.

$\overline{\text{PG}}$ OUTPUT

The open-drain $\overline{\text{PG}}$ (power Good) indicates when the AC adapter is present. The output turns ON when a valid voltage is detected. This output is turned off in the sleep mode. The $\overline{\text{PG}}$ pin can be used to drive an LED or to communicate to the host processor.

$\overline{\text{CE}}$ INPUT (CHARGE ENABLE)

The $\overline{\text{CE}}$ digital input is used to disable or enable the charge process. A low-level signal on this pin enables the charge. A high-level signal disables the charge, and places the device in a low-power mode. A high-to-low transition on this pin also resets all timers and timer fault conditions. Note that this applies to both AC and USB charging.

$\overline{\text{TTE}}$ INPUT (TIMER AND TERMINATION ENABLE)

The $\overline{\text{TTE}}$ digital input is used to disable or enable the fast-charge timer and charge-taper detection. A low-level signal on this pin enables the fast-charge timer and taper timer, and a high-level signal disables this feature. Note that this applies to both AC and USB charging.

THERMAL SHUTDOWN AND PROTECTION

The bqTINY-II monitors the junction temperature, T_J , and suspends charging if T_J exceeds $T_{(\text{SHTDWN})}$. Charging resumes when T_J falls approximately 15°C below $T_{(\text{SHTDWN})}$.

$\overline{\text{TE}}$ INPUT (TIMER ENABLED)

The $\overline{\text{TE}}$ digital input is used to disable or enable the fast-charge timer. A low-level signal on this pin enables the fast-charge timer and a high-level signal disables this feature.

Note that this applies to both AC and USB charging.

TIMER FAULT RECOVERY

As shown in [Figure 4](#), the bqTINY-II provides a recovery method to deal with timer-fault conditions. The following discussion summarizes this method:

Condition #1: The charge voltage is above the recharge threshold ($V_{(RCH)}$), and a timeout fault occurs

Recovery method: bqTINY-II waits for the battery voltage to fall below the recharge threshold. This could happen as a result of a load on the battery, self-discharge or battery removal. When the battery voltage falls below the recharge threshold, the bqTINY-II clears the fault and starts a new charge cycle. Toggling POR, $\overline{CE}$, or $\overline{TTE}$ also clears the fault.

Condition #2: The charge voltage is below the recharge threshold ($V_{(RCH)}$), and a timeout fault occurs

Recovery method: In this scenario, the bqTINY-II applies the $I_{(FAULT)}$ current. This small current is used to detect a battery-removal condition and remains on as long as the battery voltage stays below the recharge threshold. If the battery voltage goes above the recharge threshold, then the bqTINY-II disables the $I_{(FAULT)}$ current and executes the recovery method described for condition #1. When the battery voltage falls below the recharge threshold, the bqTINY-II clears the fault and starts a new charge cycle. Toggling POR, $\overline{CE}$, or $\overline{TTE}$ also clears the fault.

APPLICATION INFORMATION

THERMAL CONSIDERATIONS

The bqTINY-II is packaged in a thermally enhanced MLP package. The package includes a thermal pad to provide an effective thermal contact between the device and the printed circuit board (PCB). Full PCB design guidelines for this package are provided in the application note entitled, *QFN/SON PCB Attachment Application Note* (TI Literature Number [SLUA271](#)).

The most common measure of package thermal performance is thermal impedance (θ_{JA}) measured (or modeled) from the device junction to the air surrounding the package surface (ambient). The mathematical expression for θ_{JA} is:

$$\theta_{JA} = \frac{T_J - T_A}{P} \quad (5)$$

Where:

- T_J = device junction temperature
- T_A = ambient temperature
- P = device power dissipation

Factors that can greatly influence the measurement and calculation of θ_{JA} include:

- whether or not the device is board mounted
- trace size, composition, thickness, and geometry
- orientation of the device (horizontal or vertical)
- volume of the ambient air surrounding the device under test and airflow_lus549
- whether other surfaces are in close proximity to the device being tested

The device power dissipation, P , is a function of the charge rate and the voltage drop across the internal power FET. It can be calculated from the following equation:

$$P = (V_{IN} - V_{I(BAT)}) \times I_{O(OUT)} \quad (6)$$

Due to the charge profile of Li-xx batteries, the maximum power dissipation is typically seen at the beginning of the charge cycle when the battery voltage is at its lowest. See [Figure 2](#).

PCB LAYOUT CONSIDERATIONS

It is important to pay special attention to the PCB layout. The following provides some guidelines:

- To obtain optimal performance, the decoupling capacitor from V_{CC} to V_{SS} and the output filter capacitors from OUT to VSS should be placed as close as possible to the bqTINY, with short trace runs to both signal and V_{SS} pins.
- All low-current V_{SS} connections should be kept separate from the high-current charge or discharge paths from the battery. Use a single-point ground technique incorporating both the small-signal ground path and the power-ground path.
- The BAT pin is the voltage feedback to the device. It should be connected with its trace as close to the battery pack as possible.
- The high-current charge paths into IN and from the OUT pins must be sized appropriately for the maximum charge current in order to avoid voltage drops in these traces.
- The bqTINY-II is packaged in a thermally-enhanced MLP package. The package includes a thermal pad to provide an effective thermal contact between the device and the printed circuit board (PCB). Full PCB design guidelines for this package are provided in the application note entitled: *QFN/SON PCB Attachment Application Note* (TI Literature No. [SLUA271](#)).

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
BQ24020DRCR	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24020DRCRG4	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24022DRCR	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24022DRCRG4	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24023DRCR	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24023DRCRG4	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24024DRCR	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24024DRCRG4	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24025DRCR	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24025DRCRG4	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24026DRCR	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24026DRCRG4	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24027DRCR	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24027DRCRG4	ACTIVE	SON	DRC	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24027DRCT	ACTIVE	SON	DRC	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ24027DRCTG4	ACTIVE	SON	DRC	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

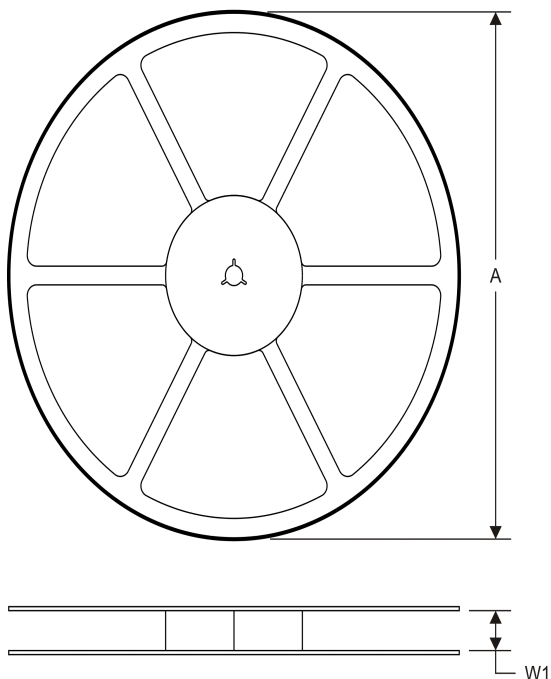
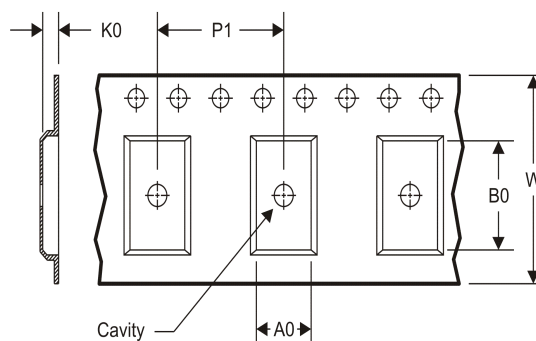
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ24020DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24020DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
BQ24022DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24022DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
BQ24023DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
BQ24023DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24024DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
BQ24024DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24025DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24025DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
BQ24026DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
BQ24026DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24027DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ24027DRCT	SON	DRC	10	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS

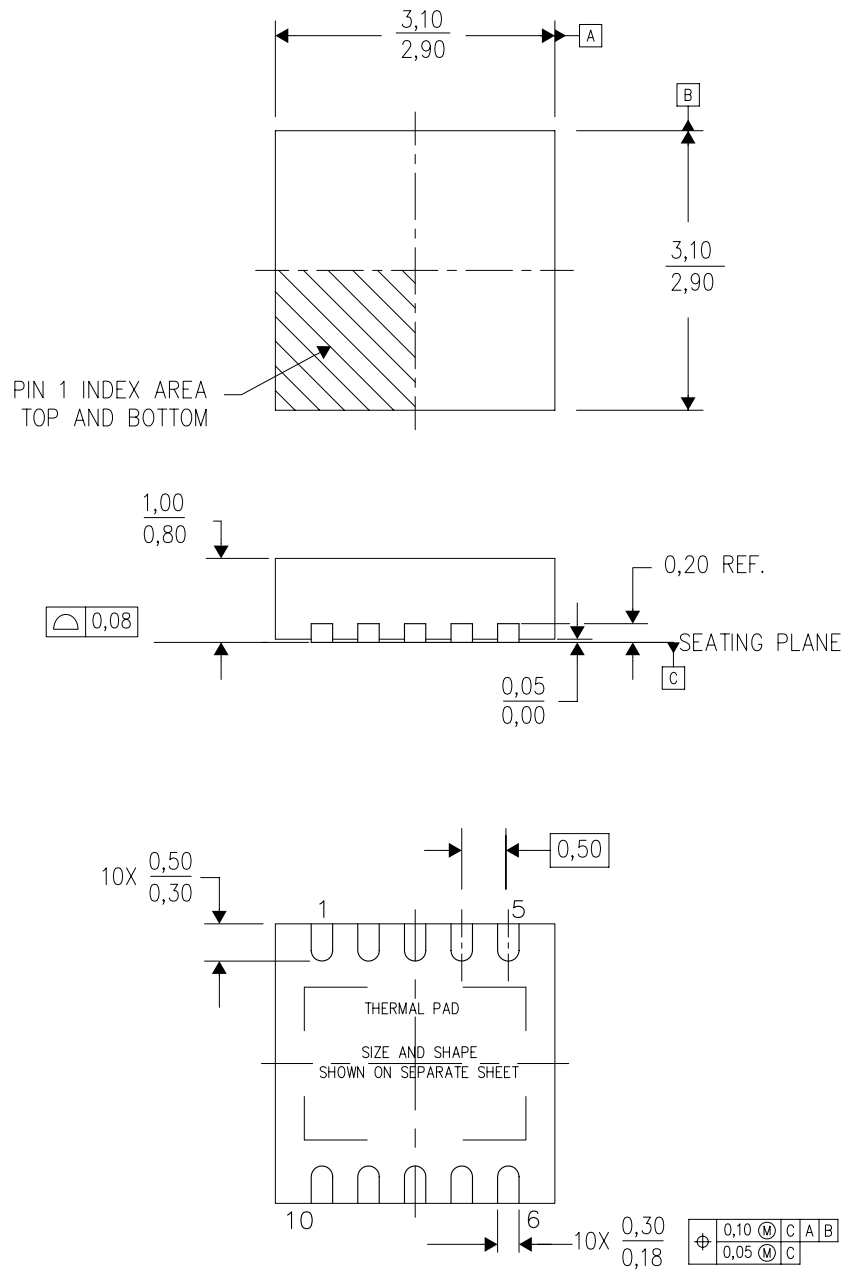


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ24020DRCR	SON	DRC	10	3000	346.0	346.0	29.0
BQ24020DRCR	SON	DRC	10	3000	370.0	355.0	55.0
BQ24022DRCR	SON	DRC	10	3000	346.0	346.0	29.0
BQ24022DRCR	SON	DRC	10	3000	370.0	355.0	55.0
BQ24023DRCR	SON	DRC	10	3000	370.0	355.0	55.0
BQ24023DRCR	SON	DRC	10	3000	346.0	346.0	29.0
BQ24024DRCR	SON	DRC	10	3000	370.0	355.0	55.0
BQ24024DRCR	SON	DRC	10	3000	346.0	346.0	29.0
BQ24025DRCR	SON	DRC	10	3000	346.0	346.0	29.0
BQ24025DRCR	SON	DRC	10	3000	370.0	355.0	55.0
BQ24026DRCR	SON	DRC	10	3000	370.0	355.0	55.0
BQ24026DRCR	SON	DRC	10	3000	346.0	346.0	29.0
BQ24027DRCR	SON	DRC	10	3000	346.0	346.0	29.0
BQ24027DRCT	SON	DRC	10	250	210.0	185.0	35.0

DRC (S-PVSON-N10)

PLASTIC SMALL OUTLINE NO-LEAD



4204102-3/L 09/11

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Small Outline No-Lead (SON) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance, if present.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions, if present

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2012, Texas Instruments Incorporated